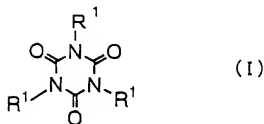


Amendments to the Claims

A full listing of the claims is as follows:

1. (Previously presented) A curable composition which contains
 - (A) an organic compound containing at least two carbon-carbon double bonds reactive with a SiH group in each molecule,
 - (B) a compound having at least two SiH groups in each molecule,
 - (C) a hydrosilylation catalyst,
 - (D) a silane coupling agent and/or an epoxy group-containing compound, and
 - (E) a silanol condensation catalyst,wherein the component (E) is a borate ester.
2. (Canceled).
3. (Previously presented) The curable composition according to Claim 1, wherein the component (D) is a silane coupling agent having at least one functional group selected from the group consisting of epoxy, methacryl, acryl, isocyanate, isocyanurate, vinyl and carbamate group and hydrolyzable silyl group in each molecule.
4. (Previously presented) The curable composition according to Claim 1, wherein the component (D) is a silane coupling agent having an epoxy group and a hydrolyzable silyl group in each molecule.
- 5-6. (Canceled).
7. (Previously presented) The curable composition according to Claim 1, wherein the component (E) is at least one species selected from the group consisting of trinormaloctadecyl borate, trinormaloctyl borate, trinormalbutyl borate, triisopropyl borate, trinormalpropyl borate, triethyl borate and trimethyl borate.

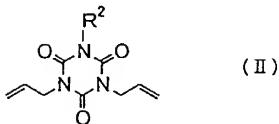
8. (Previously presented) The curable composition according to Claim 1, wherein the component (A) is a compound represented by the following general formula (I):



in the formula, each R¹ represents a univalent organic group containing 1 to 50 carbon atoms and each R¹ group may be the same or different.

9. (Previously presented) The curable composition according to Claim 1, wherein the component (A) is triallyl isocyanurate and the component (B) is a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and triallyl isocyanurate.

10. (Previously presented) The curable composition according to Claim 1, which contains a compound represented by the following general formula (II) as the component (A):



in the formula, R² represents a hydrogen atom, or an organic group which does not contain a functional group subjectable to hydrosilylation reaction.

11. (Original) The curable composition according to Claim 10, which further contains triallyl isocyanurate as the component (A).

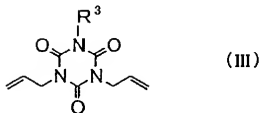
12. (Previously presented) The curable composition according to Claim 10, wherein R^2 represents a hydrogen atom, or a univalent organic group containing 1 to 50 carbon atoms.

13. (Previously presented) The curable composition according to Claim 10, wherein the compound represented by the general formula (II) accounts for 20% by weight or more in the component (A).

14. (Previously presented) The curable composition according to Claim 11, wherein the compound represented by the general formula (II) is diallyl monoglycidyl isocyanurate.

15. (Original) The curable composition according to Claim 14, wherein the component (B) is a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and triallyl isocyanurate.

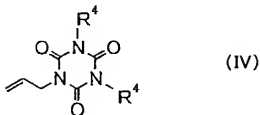
16. (Currently amended) The curable composition according to Claim 1, wherein the component (B) contains
a compound obtained by hydrosilylation reaction between a compound represented by the following general formula (III):



in the formula, R^3 represents a hydrogen atom, or an organic group which does not contain a functional group subjectable to hydrosilylation reaction: and a compound having at least two SiH groups in each molecule, and/or

a compound obtained by hydrosilylation reaction between a compound represented by the following general formula (IV):

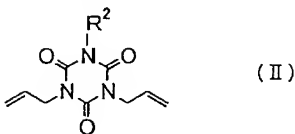
~~in the formula, R⁴ represents a hydrogen atom, or an organic group which does not~~



~~in the formula, R⁴ represents a hydrogen atom, or an organic group which does not~~
contain a functional group subjectable to hydrosilylation reaction, and each R⁴ may be the same or different: and a compound having at least three SiH groups in each molecule.

17. (Original) The curable composition according to Claim 16,
wherein R³ and R⁴ represent hydrogen atoms or univalent organic groups containing 1 to 50 carbon atoms.
18. (Original) The curable composition according to Claim 16,
wherein the component (B) contains a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and diallyl monoglycidyl isocyanurate, and/or a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and monoallyl diglycidyl isocyanurate.
19. (Original) The curable composition according to Claim 16,
wherein the component (B) contains a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and diallyl monoglycidyl isocyanurate, and/or a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and monoallyl diglycidyl isocyanurate as exclusive constituents.
20. (Previously presented) The curable composition according to Claim 16,
wherein the component (A) is triallyl isocyanurate.

21. (Previously presented) The curable composition according to Claim 16, wherein the component (A) is a mixture of triallyl isocyanurate and diallyl monoglycidyl isocyanurate.
22. (Previously presented) A curing product which is obtained by curing the curable composition according to Claim 1.
23. (Previously presented) A process for producing a curing product which comprises curing the curable composition according to Claim 1.
24. (Original) A light-emitting diode which is sealed with the curing product according to Claim 22.
25. (Previously presented) A curable composition which contains
(A) an organic compound containing at least two carbon-carbon double bonds reactive with a SiH group in each molecule,
(B) a compound having at least two SiH groups in each molecule, and
(C) a hydrosilylation catalyst,
in which a compound represented by the following general formula (II):



in the formula, R² represents a hydrogen atom, or an organic group which does not contain a functional group subjectable to hydrosilylation reaction: is contained as the component (A), and the compound represented by the general formula (II) accounts for 20% by weight or more in the component (A).

26. (Original) The curable composition according to Claim 25, which further contains triallyl isocyanurate as the component (A).
27. (Previously presented) The curable composition according to Claim 25, wherein R^2 represents a hydrogen atom, or a univalent organic group containing 1 to 50 carbon atoms.
28. (Canceled).
29. (Previously presented) The curable composition according to Claim 26, wherein the compound represented by the general formula (II) is diallyl monoglycidyl isocyanurate.
30. (Original) The curable composition according to Claim 29, wherein the component (B) is a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and triallyl isocyanurate.
31. (Previously presented) A curing product which is obtained by curing the curable composition according to Claim 25.
32. (Previously presented) A process for producing a curing product which comprises curing the curable composition according to Claim 25.
33. (Previously presented) A curable composition which contains
(A) an organic compound containing at least two carbon-carbon double bonds reactive with a SiH group in each molecule,
(B) a compound having at least two SiH groups in each molecule, and
(C) a hydrosilylation catalyst,
in which the component (B) contains a reaction product from 1, 3, 5, 7-tetramethylcyclotetrasiloxane and diallyl monoglycidyl isocyanurate, and/or a reaction product

from 1, 3, 5, 7-tetramethylcyclotetrasiloxane and monoallyl diglycidyl isocyanurate.

34-35. (Canceled).

36. (Original) The curable composition according to Claim 33, wherein the component (B) contains a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and diallyl monoglycidyl isocyanurate, and/or a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and monoallyl diglycidyl isocyanurate as exclusive constituents.

37. (Previously presented) The curable composition according to Claim 33, wherein the component (A) is triallyl isocyanurate.

38. (Previously presented) The curable composition according to Claim 33, wherein the component (A) is a mixture of triallyl isocyanurate and diallyl monoglycidyl isocyanurate.

39. (Previously presented) A curing product which is obtained by curing the curable composition according to Claim 33.

40. (Previously presented) A process for producing a curing product which comprises curing the curable composition according to Claim 33.

41. (Previously presented) A light-emitting diode which comprises a light emitting element, a substrate on the top surface of which is formed with an external electrode to be disposed with said light emitting element, and a sealing member disposed adjacently onto said substrate, the contact surface between said electrode and said sealing member being 50 to 90% when the contact surface between said substrate and said sealing member is set at 100%, and said sealing member being a curing product obtained from a curable composition

containing

(A) an organic compound containing at least two carbon-carbon double bonds reactive with a SiH group in each molecule,

(B) a compound having at least two SiH groups in each molecule,

(C) a hydrosilylation catalyst,

(D) a silane coupling agent and/or an epoxy group-containing compound, and

(E) a silanol condensation catalyst,

wherein the component (E) is a borate ester.

42. (Original) The light emitting diode according to Claim 41,
wherein the substrate is formed from a composition containing a semicrystalline polymer resin.

43. (Previously presented) A light-emitting diode
which comprises a light emitting element, a package comprising an aperture having a bottom surface to be disposed with said light emitting element and sidewalls, and a sealing member for sealing said aperture,

said package being formed of a molding resin by a monolithic process with one end of the external electrode being exposed on said aperture bottom,

the area of said external electrode on said aperture bottom being 50 to 90% when the surface area of said aperture bottom is set at 100%, and

said sealing member being a curing product obtained from a curable composition containing

(A) an organic compound containing at least two carbon-carbon double bonds reactive with a SiH group in each molecule,

(B) a compound having at least two SiH groups in each molecule,

(C) a hydrosilylation catalyst,

(D) a silane coupling agent and/or an epoxy group-containing compound, and

(E) a silanol condensation catalyst,

wherein the component (E) is a borate ester.

44. (Original) The light-emitting diode according to Claim 43,
wherein the package is formed of a molding resin by a monolithic process with the
respective ends of an external positive electrode and an external negative electrode being
exposed at a predetermined distance on the aperture bottom, and
said respective exposed external electrode on said aperture bottom having at least one
pair of resin exposure parts of the molding resin of the package.

45. (Previously presented) The light-emitting diode according to Claim 43,
wherein the molding resin of the package is a composition containing a semicrystalline
polymer resin.

46. (Previously presented) The light-emitting diode according to Claims 41 or 43,
wherein the component (D) is a silane coupling agent having at least one functional group
selected from the group consisting of epoxy, methacryl, acryl, isocyanate, isocyanurate, vinyl
and carbamate group and a hydrolyzable silyl group in each molecule.

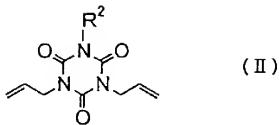
47-48. (Canceled).

49. (Previously presented) The light-emitting diode according to Claims 41 or 43,
wherein the component (E) is at least one species selected from the group consisting of
trinormaloctadecyl borate, trinormaloctyl borate, trinormalbutyl borate, triisopropyl borate,
trinormalpropyl borate, triethyl borate and trimethyl borate.

50. (Previously presented) The light-emitting diode according to Claims 41 or 43,
wherein the component (A) is triallyl isocyanurate and the component (B) is a reaction
product from 1,3,5,7-tetramethylcyclotetrasiloxane and triallyl isocyanurate.

51. (Previously presented) The light-emitting diode according to Claims 41 or 43,
wherein the curable composition contains a compound represented by the following

general formula (II) as the component (A):



in the formula, R² represents a hydrogen atom, or an organic group which does not contain a functional group subjectable to hydrosilylation reaction.

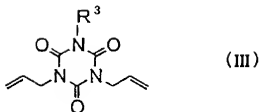
52. (Original) The light-emitting diode according to Claim 51, wherein the curable composition further contains triallyl isocyanurate as the component (A).

53. (Previously presented) The light-emitting diode according to Claim 51, wherein the compound represented by the general formula (II) accounts for 20% by weight or more in the component (A).

54. (Previously presented) The light-emitting diode according to Claim 51, wherein the compound represented by the general formula (II) is diallyl monoglycidyl isocyanurate.

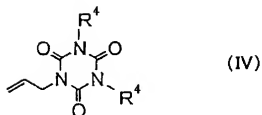
55. (Original) The light-emitting diode according to Claim 54, wherein the component (B) is a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and triallyl isocyanurate.

56. (Previously presented) The light-emitting diode according to Claims 41 or 43, wherein the component (B) contains a compound obtained by hydrosilylation reaction between a compound represented by the following general formula (III):



in the formula, R³ represents a hydrogen atom, or an organic group which does not contain a functional group subjectable to hydrosilylation reaction: and a compound having at least two SiH groups in each molecule, and/or

a compound obtained by hydrosilylation reaction between a compound represented by the following general formula (IV):



in the formula, R⁴ represents a hydrogen atom, or an organic group which does not contain a functional group subjectable to hydrosilylation reaction and each R⁴ may be the same or different: and a compound having at least three SiH groups in each molecule.

57. (Original) The light-emitting diode according to Claim 56, wherein the component (B) contains a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and diallyl monoglycidyl isocyanurate, and/or a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and monoallyl diglycidyl isocyanurate.

58. (Original) The light-emitting diode according to Claim 56, wherein the curable composition contains, as the component (B), a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and diallyl monoglycidyl isocyanurate, and/or a reaction product from 1,3,5,7-tetramethylcyclotetrasiloxane and monoallyl diglycidyl isocyanurate as

exclusive constituents.

59. (Previously presented) The light-emitting diode according to Claim 56, wherein the component (A) is triallyl isocyanurate.

60. (Previously presented) The light-emitting diode according to Claim 56, wherein the component (A) is a mixture of triallyl isocyanurate and diallyl monoglycidyl isocyanurate.

61. (Previously presented) A light-emitting diode which comprises a light emitting element, a package comprising an aperture having a bottom surface to be disposed with said light emitting element and sidewalls, and a sealing member for sealing said aperture,

said package being formed of a molding resin by a monolithic process with one end of the external electrode being exposed on said aperture bottom,

the area of said external electrode on said aperture bottom being 50 to 90% when the surface area of said aperture bottom is set at 100%, and

said sealing member containing the curing product according to Claims 31 or 39.

62. (Original) The light-emitting diode according to Claim 61, wherein the package is formed of a molding resin by a monolithic process with the respective ends of an external positive electrode and an external negative electrode being exposed at a predetermined distance on the aperture bottom, and

said respective exposed external electrode on said aperture bottom having at least one pair of resin exposure parts of the molding resin of the package.

63. (Previously presented) The light-emitting diode according to Claim 61, wherein the molding resin of the package is a composition containing a semicrystalline polymer resin.